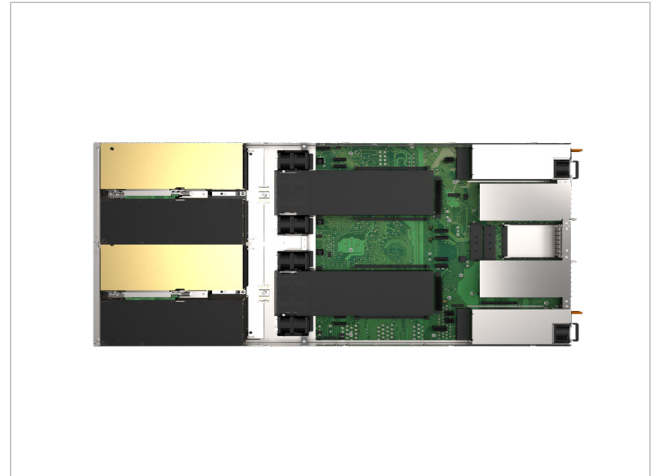
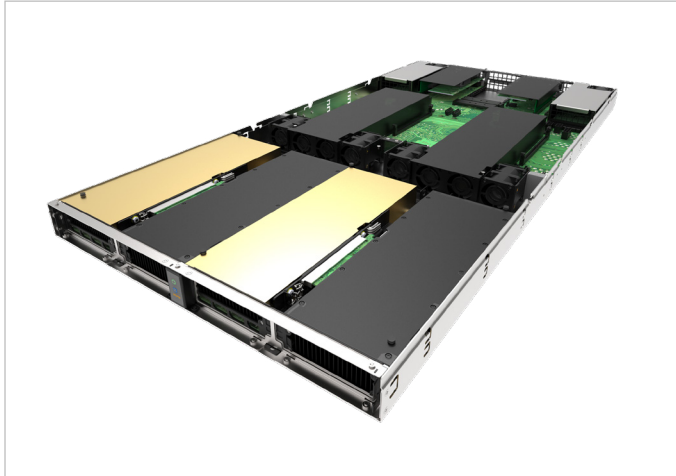


Godì 1.4 SP5-D

1U High-Density Platform for AI, FPGA & GPU Acceleration



Key Features



19-inch 1U



**Dual AMD EPYC™
9004/9005 Socket SP5**



**24 DDR5 slots
Up to 6400MT/s**



**4x PCIe 5.0 x16 DW FH-FL
2x PCIe 5.0 x16 HH-HL
1x PCIe 5.0 x16 OCP 3.0**



Air cooling

PRODUCT PAGE

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TO DISCOVER MORE
ABOUT THIS PRODUCT

Godì 1.4 SP5-D – Heterogeneous Acceleration in 1U

The Godì 1.4 SP5-D is a high-density dual-socket server engineered for heterogeneous accelerated computing in a compact 1U form factor. Combining dual AMD EPYC™ 9004/9005 processors, up to 24 DDR5 DIMMs and extensive PCIe Gen 5 connectivity, the platform delivers the compute, memory bandwidth and I/O required by modern accelerator-intensive workloads.

Its architecture supports up to four double-width, full-height, full-length PCIe accelerators, enabling GPU, FPGA and dedicated AI acceleration within the same server platform. This makes the Godì 1.4 SP5-D well suited to AI inference, computer vision, network acceleration, low-latency computing, cybersecurity and GPU-accelerated applications.

Purpose-Built for GPU, FPGA and AI Accelerators

Rather than being designed as a generic PCIe server, the Godì 1.4 SP5-D has been developed around demanding accelerator configurations. Its mechanical architecture, PCIe topology, power delivery and thermal design have been optimized together to efficiently integrate high-performance accelerator cards within a 1U chassis.

The platform is particularly suited to configurations based on REFLEX CES XpressGX S10-FH800G, Axelera Europa 1-chip and 4-chip solutions, and NVIDIA L40S GPUs. This heterogeneous approach allows each workload to use the acceleration technology best suited to its performance, latency and efficiency requirements.

Advanced Air Cooling for Sustained High-Density Performance

Delivering this level of accelerator density in 1U requires a carefully engineered thermal architecture. The Godì 1.4 SP5-D uses a high-performance air-cooling system designed for sustained operation with high-power CPUs and accelerator cards.

The internal layout creates controlled front-to-back airflow across the most demanding components, while high-performance fans and optimized airflow paths help reduce thermal hotspots and recirculation.

This architecture allows customers to deploy dense accelerated computing without requiring liquid-cooling infrastructure, preserving the simplicity, serviceability and flexibility of conventional air-cooled data centers.

Versatile Workloads from Edge AI to Accelerated Computing

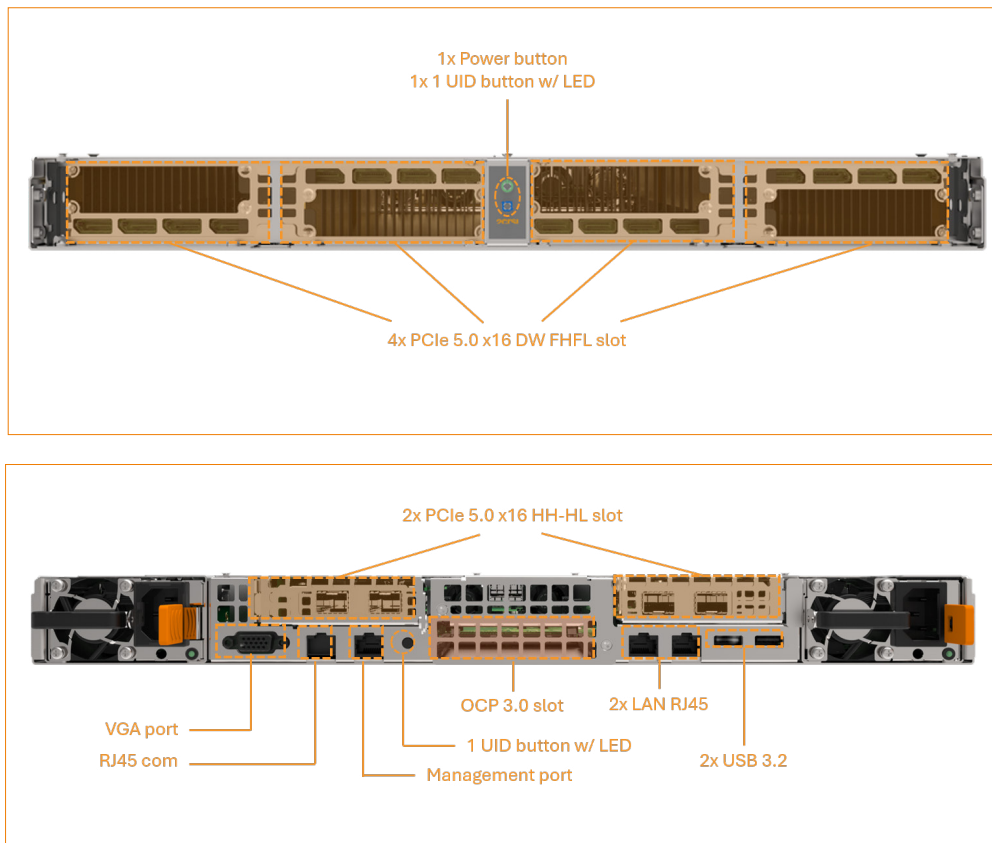
The Godì 1.4 SP5-D is designed for a wide range of accelerated workloads, including AI inference, computer vision, video analytics, FPGA-based processing, network acceleration, cybersecurity and GPU computing. Its flexible architecture makes it equally suitable for centralized data centers, edge deployments, industrial environments and defense applications requiring high performance, low latency and efficient use of rack space.

Godì 1.4 SP5-D

SPECIFICATIONS

System	SKU	BRB-GI1-104-SP5D-R1000
	Model	Godì 1.4 SP5-D
	Form factor	19-inch 1U
	Dimension	438 mm x 900 mm x 440 (W x D x H) 17.24" x 35.43" x 1.75" (W x D x H)
	Cooling Technology	Air cooling
Storage	Internal type	2x M.2 NVMe PCIe 3.0 x4 2280 Optional : Low-Profile M.2 Storage Adapter, for 2x M.2 NVMe PCIe 4.0/5.0 x4 2280/22110
	RAID controller	Optional: Low-Profile M.2 RAID Boot Storage Adapter, RAID 0/1 for 2x M.2 NVMe PCIe 3.0/4.0 x2 2280/22110
Motherboard	CPU	Support AMD EPYC™ 9xx5/9xx4 Turin, Genoa, Bergamo and Genoa-X with AMD 3D V-Cache™ Technology Series Processor families, Dual Socket SP5, cTDP up to 210W (with 4 GPUs at 350W).
	Chipset	System on Chip
	Expansion slots (rear)	Front: 4x PCIe 5.0 x16 for Dual-Width FH-FL slot (e.g Nvidia L40S, Reflex CES XpressGX S10-FH800G, Axelera Europa 1 chips & Axelera Europa 4 chips) <i>Note : it can accommodate other accelerators through faceplate customization</i> Rear: 2x PCIe 5.0 x16 Single-Width HH-HL slot 1x PCIe 5.0 x16 OCP v3.0 LAN mezzanine slot
	TPM	TPM header with SPI interface (optional TPM2.0 kit available)
	BMC	ASPEED AST2600
	Memory	24x DIMM slot (12 channels per CPU)
Memory	Capacity	Up to 6TB, from 16GB to 256GB per module RDIMM: 128GB (2Rx4) RDIMM-3DS: 256GB (2Rx4)
	Memory type	AMD EPYC™ 9005: DDR5 RDIMM 6400 MT/s (1DPC) / 5200 MT/s (2DPC) AMD EPYC™ 9004: DDR5 RDIMM 4800 MT/s
	Network	1x 1GbE Management Port dedicated to the IPMI
I/O	Front	1x Power button 1x UID button w/ LED
	Rear	2x USB 3.2 Port (Type A) 1x SVGA 1x DB-9 COM 2x RJ45 1x RJ45 dedicated IPMI 1x UID button w/ LED
Management solution	Software	WebGUI, IPMI 2.0 and RESTful APIs (Redfish)
	Out of band remote management	iKVM module
Power supply	Type	1+2 2200 W 80 PLUS Titanium redundant power supplies
Operating environment	Operating temperature	10°C ~ 35°C (50°F ~ 95°F)
	Non-operating temperature	-40°C ~ 70°C (40° ~ 158°F)
	Operative relative humidity	N/A
	Non-operating relative Humidity	95%, non-condensing at 35° C
Warranty	2CRSi hardware warranty includes a one year, parts and labour with return to 2CRSi selling entity. Customers may purchase an extended warranty of up to 3 years on parts and labour with different support levels. Please contact 2CRSi at support@2crsi.com or reach your sales point of contact for complete warranty details including limitations and transferability. 2crsi.com/global-location	

Godì 1.4 SP5-D



BLOCK DIAGRAM

